



Material Content Data Sheet



Sales Product Name		BTS711L1		Issued		29. August 2013		
MA#		MA000999040						
Package		PG-DSO-20-59		Weight*		499.35 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	9.157	1.83	1.83	18338	18338
leadframe	non noble metal	zinc	7440-66-6	0.169	0.03		339	
	inorganic material	phosphorus	7723-14-0	0.042	0.01		85	
	non noble metal	iron	7439-89-6	3.388	0.68		6785	
	non noble metal	copper	7440-50-8	137.580	27.55	28.27	275517	282726
wire	noble metal	gold	7440-57-5	1.932	0.39	0.39	3868	3868
encapsulation	organic material	carbon black	1333-86-4	0.677	0.14		1356	
	plastics	epoxy resin	-	31.137	6.24		62355	
	inorganic material	silicondioxide	60676-86-0	306.630	61.40	67.78	614058	677769
leadfinish	non noble metal	tin	7440-31-5	2.746	0.55	0.55	5499	5499
plating	noble metal	silver	7440-22-4	3.476	0.70	0.70	6962	6962
glue	plastics	epoxy resin	-	0.423	0.08		847	
	noble metal	silver	7440-22-4	1.993	0.40	0.48	3991	4838
*deviation	< 10%					Sum in total:	100,00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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